

# DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

SDLS119 - DECEMBER 1983 - REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

## description

These devices contain two independent D-type positive-edge-triggered flip-flops. A low level at the preset or clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the D input meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the D input may be changed without affecting the levels at the outputs.

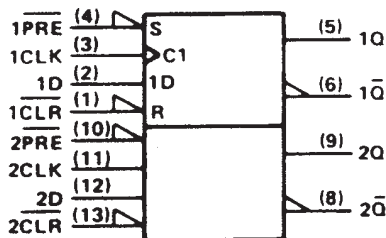
The SN54' family is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74' family is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS				OUTPUTS	
PRE	CLR	CLK	D	Q	$\bar{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H <sup>†</sup>	H <sup>†</sup>
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q <sub>0</sub>	$\bar{Q}$ <sub>0</sub>

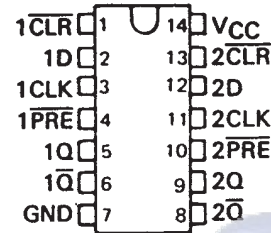
† The output levels in this configuration are not guaranteed to meet the minimum levels in V<sub>OH</sub> if the lows at preset and clear are near V<sub>IL</sub> maximum. Furthermore, this configuration is nonstable; that is, it will not persist when either preset or clear returns to its inactive (high) level.

## logic symbol<sup>‡</sup>

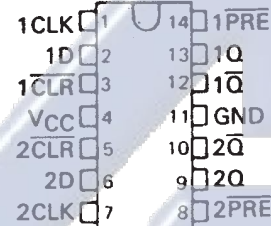


<sup>‡</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

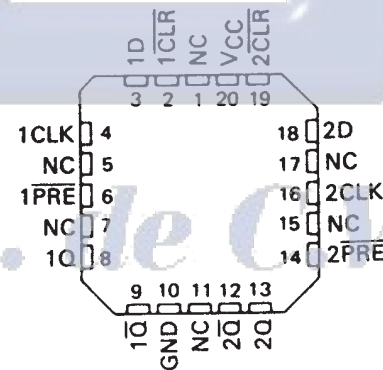
- SN5474 . . . J PACKAGE
- SN54LS74A, SN54S74 . . . J OR W PACKAGE
- SN7474 . . . N PACKAGE
- SN74LS74A, SN74S74 . . . D OR N PACKAGE



- SN5474 . . . W PACKAGE

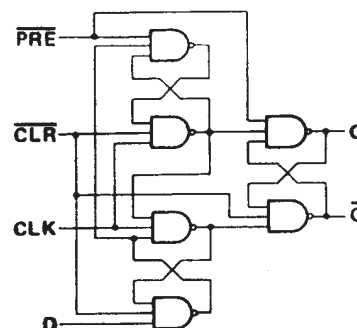


- SN54LS74A, SN54S74 . . . FK PACKAGE



NC - No internal connection

## logic diagram (positive logic)



SN5474, SN54LS74A, SN54S74

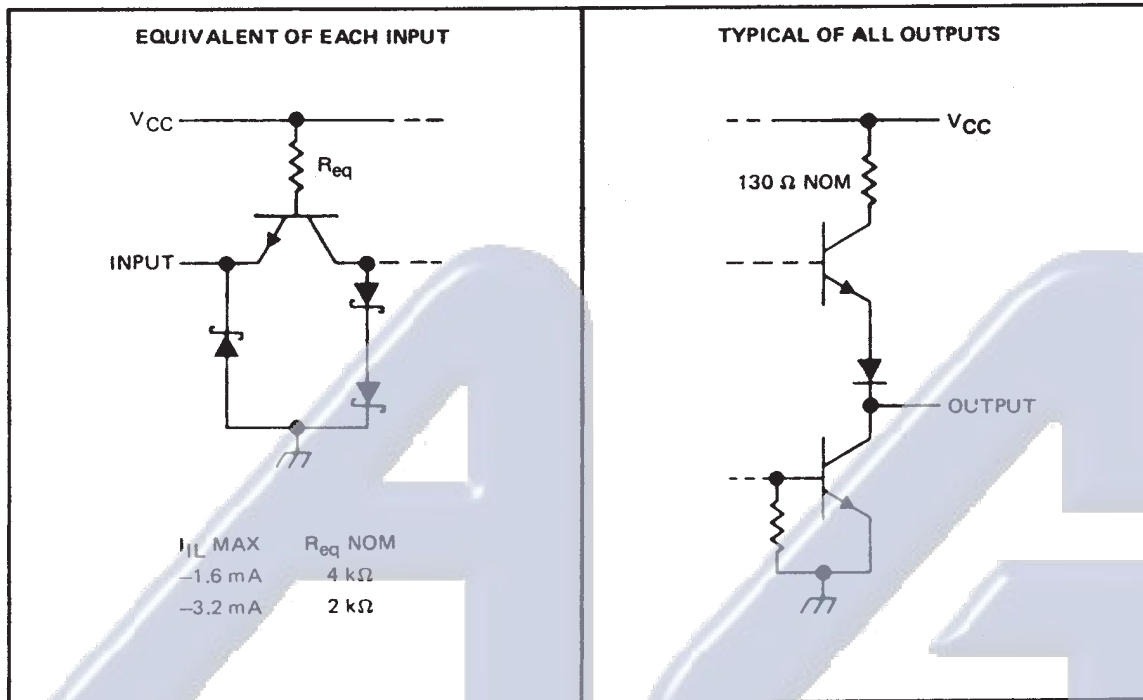
SN7474, SN74LS74A, SN74S74

DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

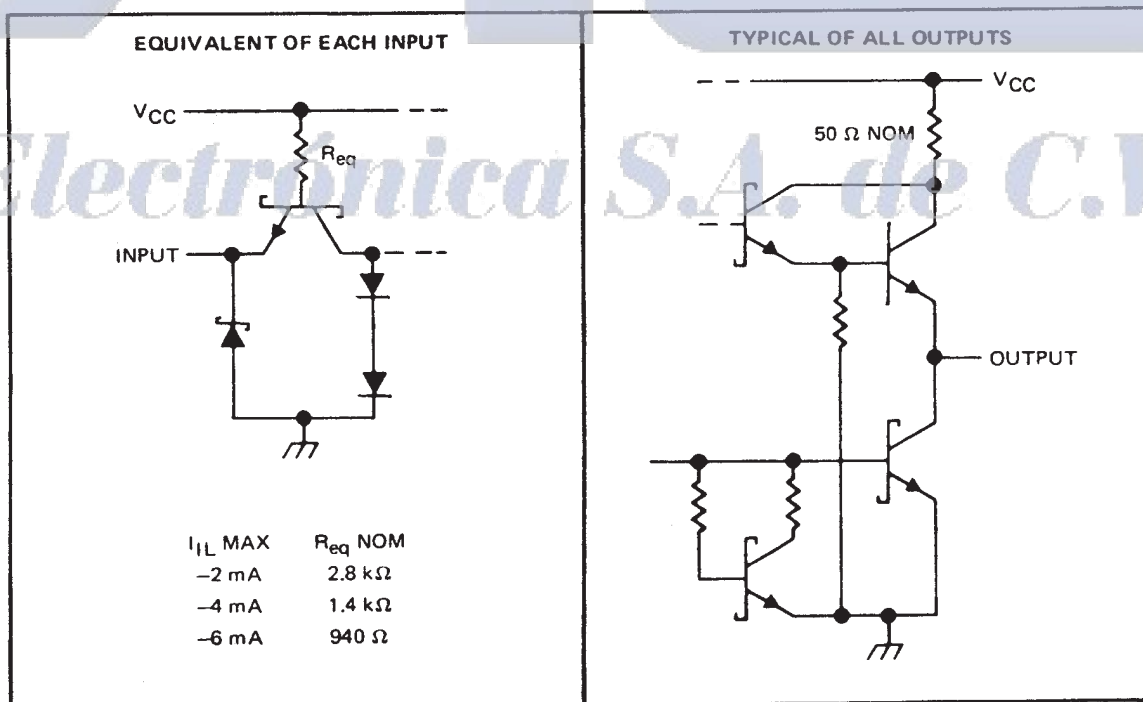
SDLS119 - DECEMBER 1983 - REVISED MARCH 1988

schematics of inputs and outputs

74



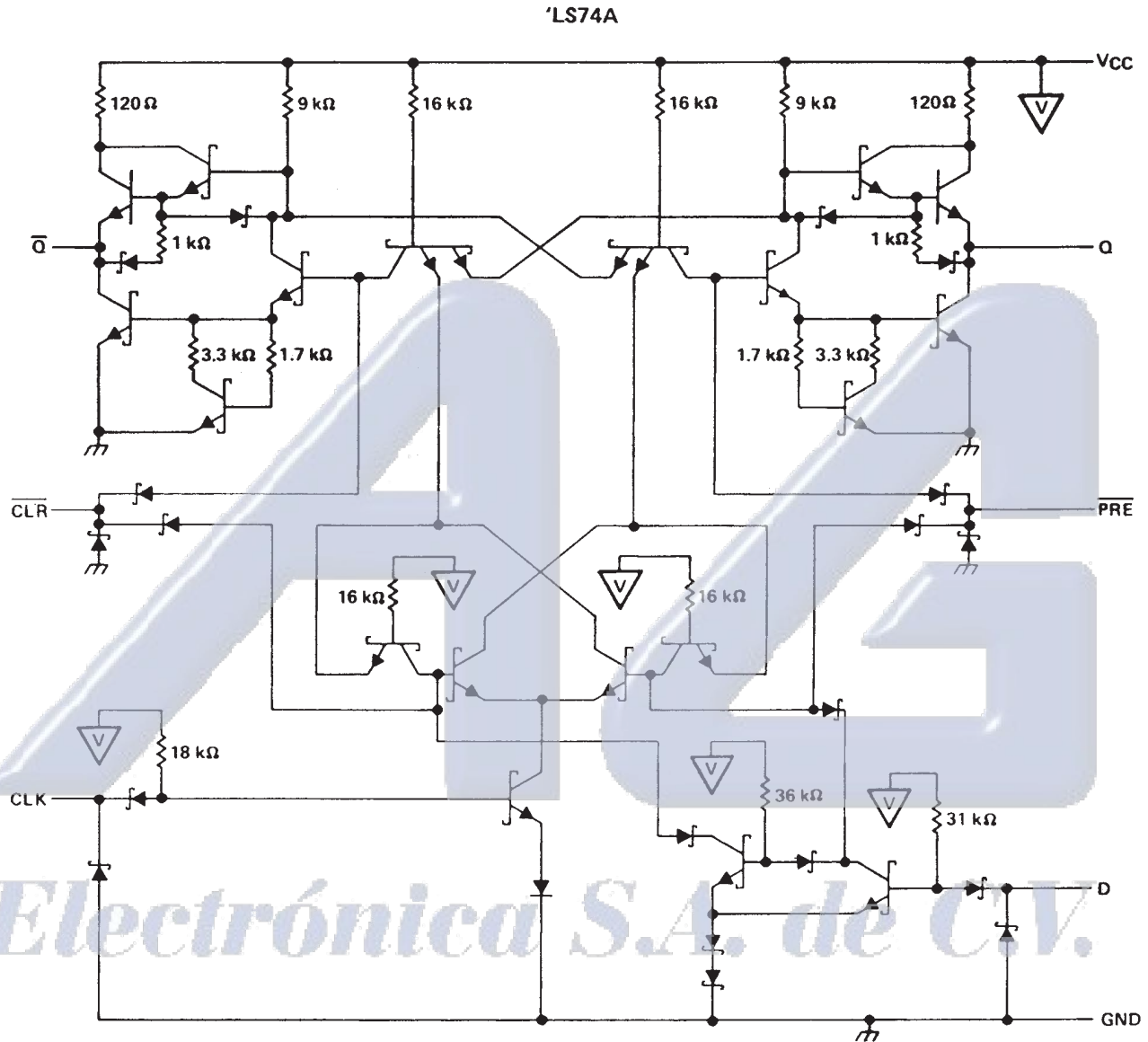
'S74



DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

SDLS119 - DECEMBER 1983 - REVISED MARCH 1988

schematic



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (see Note 1) .....	7 V
Input voltage: '74, 'S74 .....	5.5 V
'LS74A .....	7 V
Operating free-air temperature range: SN54' .....	-55°C to 125°C
SN74' .....	0°C to 70°C
Storage temperature range .....	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

SN5474, SN54LS74A, SN54S74

SN7474, SN74LS74A, SN74S74

## DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

SDLS119 – DECEMBER 1983 – REVISED MARCH 1988

## recommended operating conditions

		SN5474			SN7474			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.8			0.8	V
I <sub>OH</sub>	High-level output current			-0.4			-0.4	mA
I <sub>OL</sub>	Low-level output current			16			16	mA
t <sub>w</sub>	Pulse duration	CLK high		30	30		ns	
		CLK low		37	37			
		PRE or CLR low		30	30			
t <sub>SU</sub>	Input setup time before CLK ↑	20			20			ns
t <sub>H</sub>	Input hold time-data after CLK ↑	5			5			ns
T <sub>A</sub>	Operating free-air temperature	-55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN5474			SN7474			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -12 mA			-1.5			-1.5	V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -0.4 mA	2.4	3.4		2.4	3.4		V
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 16 mA		0.2	0.4		0.2	0.4	V
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V			1			1	mA
I <sub>IH</sub>	D			40			40	μA
	CLR			120			120	
	All Other	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.4 V		80			80	
I <sub>IL</sub>	D			-1.6			-1.6	mA
	PRE‡	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V		-1.6			-1.6	
	CLR‡			-3.2			-3.2	
	CLK			-3.2			-3.2	
I <sub>OS</sub> †	V <sub>CC</sub> = MAX	-20		-57	-18		-57	mA
I <sub>CC</sub> #	V <sub>CC</sub> = MAX, See Note 2		8.5	15		8.5	15	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§Clear is tested with preset high and preset is tested with clear high.

†Not more than one output should be shown at a time.

#Average per flip-flop.

NOTE 2: With all outputs open, I<sub>CC</sub> is measured with the Q and Q̄ outputs high in turn. At the time of measurement, the clock input is grounded.switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>				15	25		MHz
t <sub>PLH</sub>	PRE or CLR	Q or Q̄	R <sub>L</sub> = 400 Ω, C <sub>L</sub> = 15 pF			25	ns
t <sub>PHL</sub>						40	ns
t <sub>PLH</sub>	CLK	Q or Q̄			14	25	ns
t <sub>PHL</sub>					20	40	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

## DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

SDLS119 – DECEMBER 1983 – REVISED MARCH 1988

## recommended operating conditions

		SN54LS74A			SN74LS74A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
$V_{IH}$	High-level input voltage	2			2			V
$V_{IL}$	Low-level input voltage			0.7			0.8	V
$I_{OH}$	High-level output current			-0.4			-0.4	mA
$I_{OL}$	Low-level output current			4			8	mA
$f_{clock}$	Clock frequency	0		25	0		25	MHz
$t_w$	Pulse duration	CLK high		25			25	ns
		PRE or CLR low		25			25	
$t_{su}$	Setup time-before CLK $\uparrow$	High-level data		20			20	ns
		Low-level data		20			20	
$t_h$	Hold time-data after CLK $\uparrow$			5			5	ns
$T_A$	Operating free-air temperature	-55		125	0		70	$^{\circ}$ C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS <sup>†</sup>	SN54LS74A			SN74LS74A			UNIT
		MIN	TYP <sup>‡</sup>	MAX	MIN	TYP <sup>‡</sup>	MAX	
$V_{IK}$	$V_{CC} = \text{MIN}$ , $I_I = -18 \text{ mA}$			-1.5			-1.5	V
$V_{OH}$	$V_{CC} = \text{MIN}$ , $I_{OH} = -0.4 \text{ mA}$ $V_{IH} = 2 \text{ V}$ , $V_{IL} = \text{MAX}$	2.5	3.4		2.7	3.4		V
$V_{OL}$	$V_{CC} = \text{MIN}$ , $I_{OL} = 4 \text{ mA}$ $V_{IL} = \text{MAX}$ , $V_{IH} = 2 \text{ V}$		0.25	0.4		0.25	0.4	V
	$V_{CC} = \text{MIN}$ , $I_{OL} = 8 \text{ mA}$ $V_{IL} = \text{MAX}$ , $V_{IH} = 2 \text{ V}$					0.35	0.5	
$I_I$	D or CLK CLR or PRE	$V_{CC} = \text{MAX}$ , $V_I = 7 \text{ V}$		0.1	0.1		mA	
				0.2	0.2			
$I_{IH}$	D or CLK CLR or PRE	$V_{CC} = \text{MAX}$ , $V_I = 2.7 \text{ V}$		20	20		$\mu$ A	
				40	40			
$I_{IL}$	D or CLK CLR or PRE	$V_{CC} = \text{MAX}$ , $V_I = 0.4 \text{ V}$		-0.4	-0.4		mA	
				-0.8	-0.8			
$I_{OS}$ <sup>§</sup>	$V_{CC} = \text{MAX}$ , See Note 4	-20	-100	-20	-100		mA	
$I_{CC}$ (Total)	$V_{CC} = \text{MAX}$ , See Note 2	4	8	4	8		mA	

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open,  $I_{CC}$  is measured with the Q and  $\bar{Q}$  outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with  $V_O = 2.25 \text{ V}$  and  $2.125 \text{ V}$  for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

switching characteristics,  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$  (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$f_{max}$				25	33		MHz
$t_{PLH}$	CLR, PRE or CLK	Q or $\bar{Q}$	$R_L = 2 \text{ k}\Omega$ , $C_L = 15 \text{ pF}$		13	25	ns
$t_{PHL}$					25	40	ns

Note 3: Load circuits and voltage waveforms are shown in Section 1.



SN5474, SN54LS74A, SN54S74

SN7474, SN74LS74A, SN74S74

## DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

SDLS119 – DECEMBER 1983 – REVISED MARCH 1988

## recommended operating conditions

		SN54S74			SN74S74			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.8			0.8	V
I <sub>OH</sub>	High-level output current			-1			-1	mA
I <sub>OL</sub>	Low-level output current			20			20	mA
t <sub>w</sub>	Pulse duration	CLK high		6	6		ns	
		CLK low		7.3	7.3			
		CLR or PRE low		7	7			
t <sub>su</sub>	Setup time, before CLK ↑	High-level data		3	3		ns	
		Low-level data		3	3			
t <sub>h</sub>	Input hold time - data after CLK ↑	2		2		ns		
T <sub>A</sub>	Operating free-air temperature	-55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54S74			SN74S74			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA,			-1.2			-1.2	V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -1 mA	2.5	3.4		2.7	3.4		V
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 20 mA			0.5			0.5	V
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V			1			1	mA
I <sub>IH</sub>	D			50			50	μA
	CLR	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V		150			150	
	PRE or CLK			100			100	
I <sub>IL</sub>	D	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5 V		-2			-2	mA
	CLR‡			-6			-6	
	PRE‡			-4			-4	
	CLK			-4			-4	
I <sub>OS</sub> §	V <sub>CC</sub> = MAX	-40		-100	-40		-100	mA
I <sub>CC</sub> #	V <sub>CC</sub> = MAX, See Note 2	15		25	15		25	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

¶Clear is tested with preset high and preset is tested with clear high.

#Average per flip-flop.

NOTE 2: With all outputs open, I<sub>CC</sub> is measured with the Q and Q̄ outputs high in turn. At the time of measurement, the clock input is grounded.switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>				75	110		MHz
t <sub>PLH</sub>	PRE or CLR	Q or Q̄	R <sub>L</sub> = 280 Ω, C <sub>L</sub> = 15 pF		4	6	ns
t <sub>PHL</sub>	PRE or CLR (CLK high)	Q̄ or Q		9	13.5		ns
	PRE or CLR (CLK low)			5	8		
t <sub>PLH</sub>	CLK	Q or Q̄		6	9		ns
t <sub>PHL</sub>			6	9		ns	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

24-Jan-2013

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
JM38510/00205BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
JM38510/00205BDA	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125		
JM38510/07101BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07101BCA	<a href="#">Samples</a>
JM38510/07101BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07101BDA	<a href="#">Samples</a>
JM38510/30102B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30102B2A	<a href="#">Samples</a>
JM38510/30102BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30102BCA	<a href="#">Samples</a>
JM38510/30102BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30102BDA	<a href="#">Samples</a>
JM38510/30102SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/30102S CA	<a href="#">Samples</a>
JM38510/30102SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/30102S DA	<a href="#">Samples</a>
M38510/07101BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07101BCA	<a href="#">Samples</a>
M38510/07101BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07101BDA	<a href="#">Samples</a>
M38510/30102B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30102B2A	<a href="#">Samples</a>
M38510/30102BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30102BCA	<a href="#">Samples</a>
M38510/30102BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30102BDA	<a href="#">Samples</a>
M38510/30102SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/30102S CA	<a href="#">Samples</a>
M38510/30102SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/30102S DA	<a href="#">Samples</a>
SN5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SN54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS74AJ	<a href="#">Samples</a>

24-Jan-2013

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN54S74J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S74J	<a href="#">Samples</a>
SN7474DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN7474N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7474N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS74AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	<a href="#">Samples</a>
SN74LS74ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	<a href="#">Samples</a>
SN74LS74ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	<a href="#">Samples</a>
SN74LS74ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	<a href="#">Samples</a>
SN74LS74ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	<a href="#">Samples</a>
SN74LS74ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	<a href="#">Samples</a>
SN74LS74ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	<a href="#">Samples</a>
SN74LS74ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	<a href="#">Samples</a>
SN74LS74ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	<a href="#">Samples</a>
SN74LS74AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS74AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS74AN	<a href="#">Samples</a>
SN74LS74AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS74ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS74AN	<a href="#">Samples</a>
SN74LS74ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS74A	<a href="#">Samples</a>
SN74LS74ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS74A	<a href="#">Samples</a>
SN74S74D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S74	<a href="#">Samples</a>



24-Jan-2013

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74S74DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S74	<a href="#">Samples</a>
SN74S74DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S74	<a href="#">Samples</a>
SN74S74N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S74N	<a href="#">Samples</a>
SN74S74N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74S74NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S74N	<a href="#">Samples</a>
SN74S74NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74S74	<a href="#">Samples</a>
SN74S74NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74S74	<a href="#">Samples</a>
SN74S74NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74S74	<a href="#">Samples</a>
SNJ5474J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SNJ5474W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS74AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 74AFK	<a href="#">Samples</a>
SNJ54LS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS74AJ	<a href="#">Samples</a>
SNJ54LS74AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS74AW	<a href="#">Samples</a>
SNJ54S74FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 74FK	<a href="#">Samples</a>
SNJ54S74J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S74J	<a href="#">Samples</a>
SNJ54S74W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S74W	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> Only one of markings shown within the brackets will appear on the physical device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN5474, SN54LS74A, SN54LS74A-SP, SN54S74, SN7474, SN74LS74A, SN74S74 :**

● Catalog: [SN7474](#), [SN74LS74A](#), [SN54LS74A](#), [SN74S74](#)

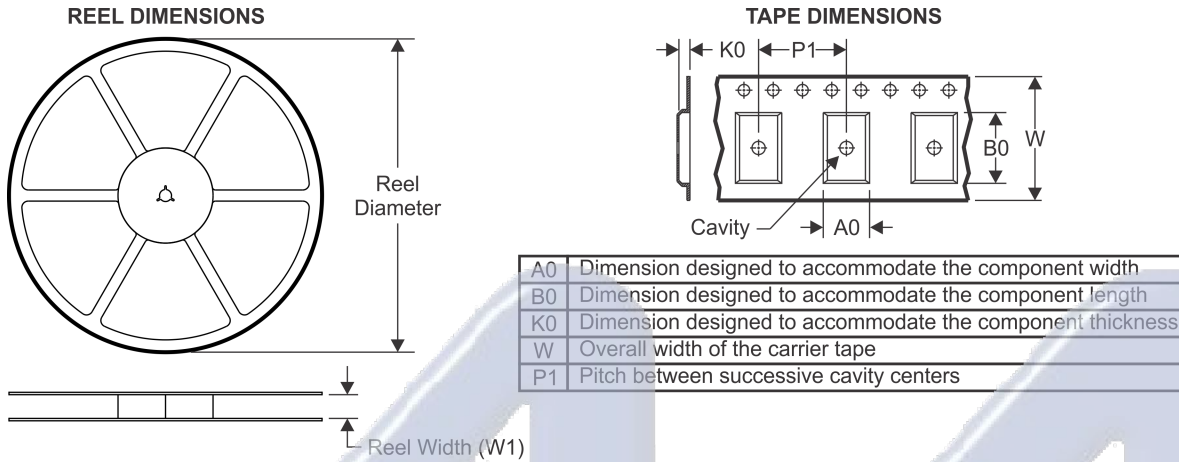
● Military: [SN5474](#), [SN54LS74A](#), [SN54S74](#)

● Space: [SN54LS74A-SP](#)

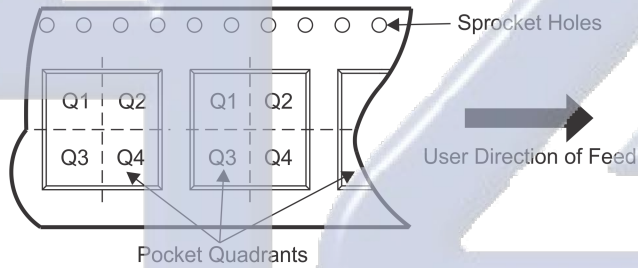
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

**TAPE AND REEL INFORMATION**



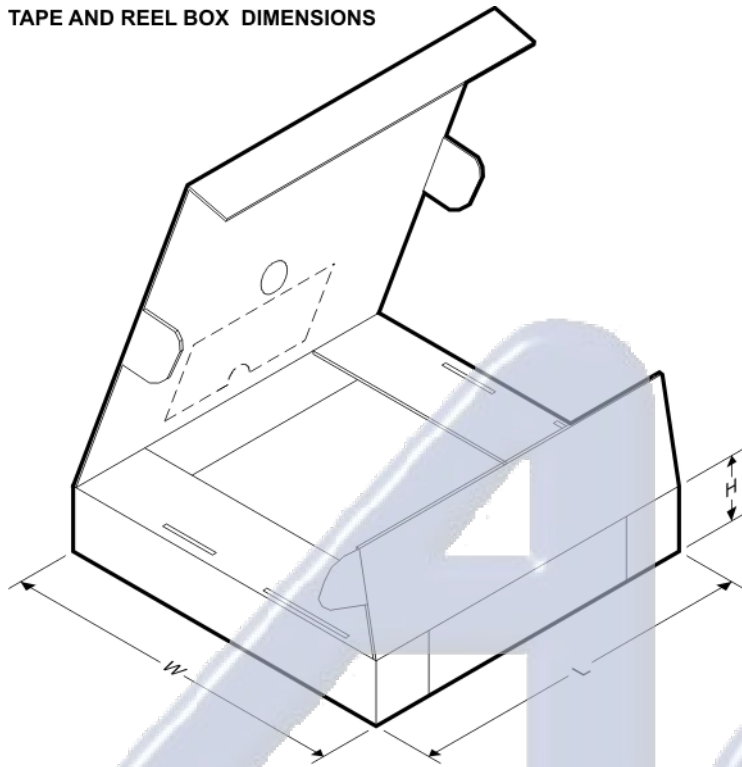
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS74ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LS74ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74S74NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



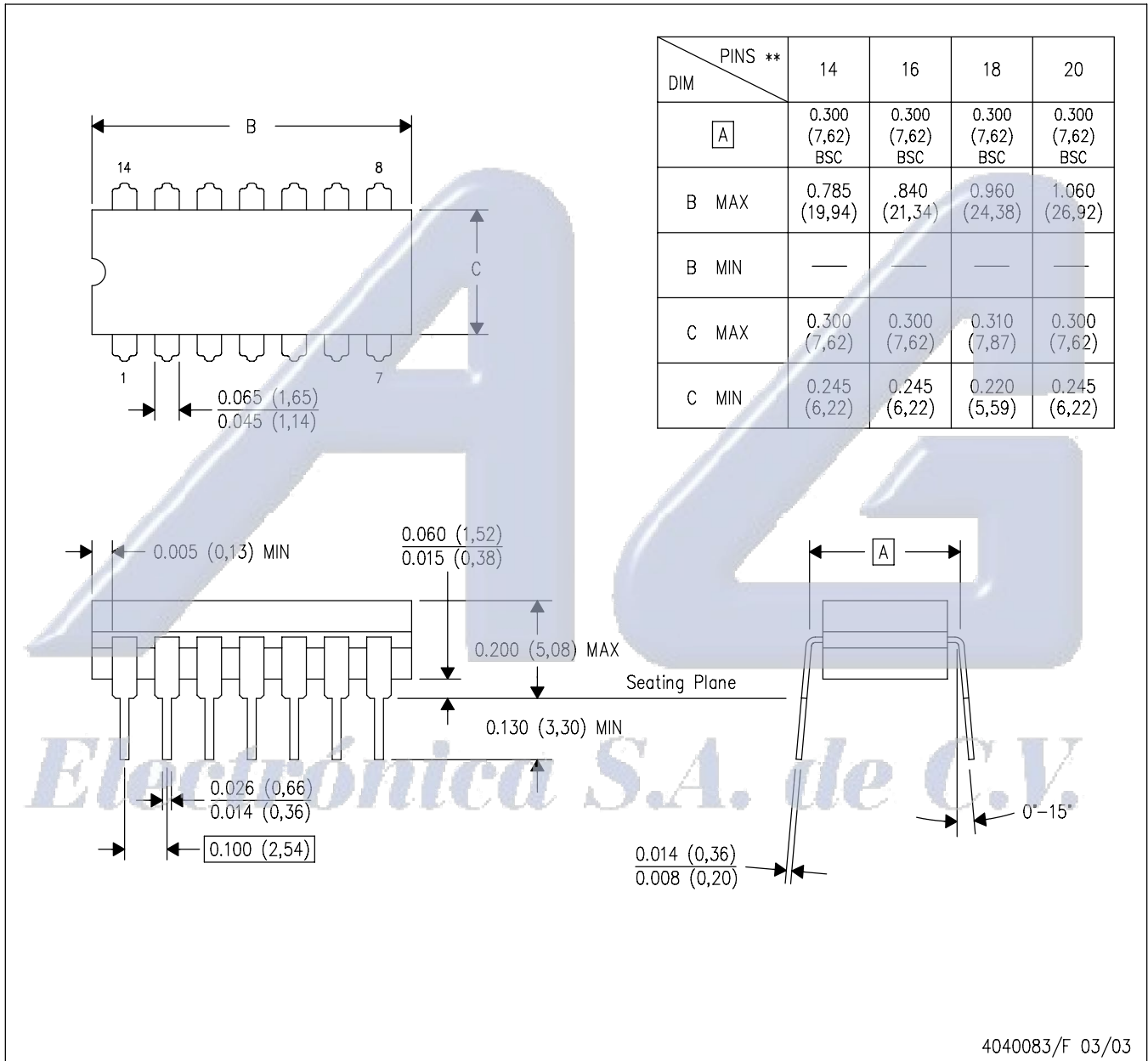
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS74ADBR	SSOP	DB	14	2000	367.0	367.0	38.0
SN74LS74ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN74S74NSR	SO	NS	14	2000	367.0	367.0	38.0

*Electrónica S.A. de C.V.*

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE

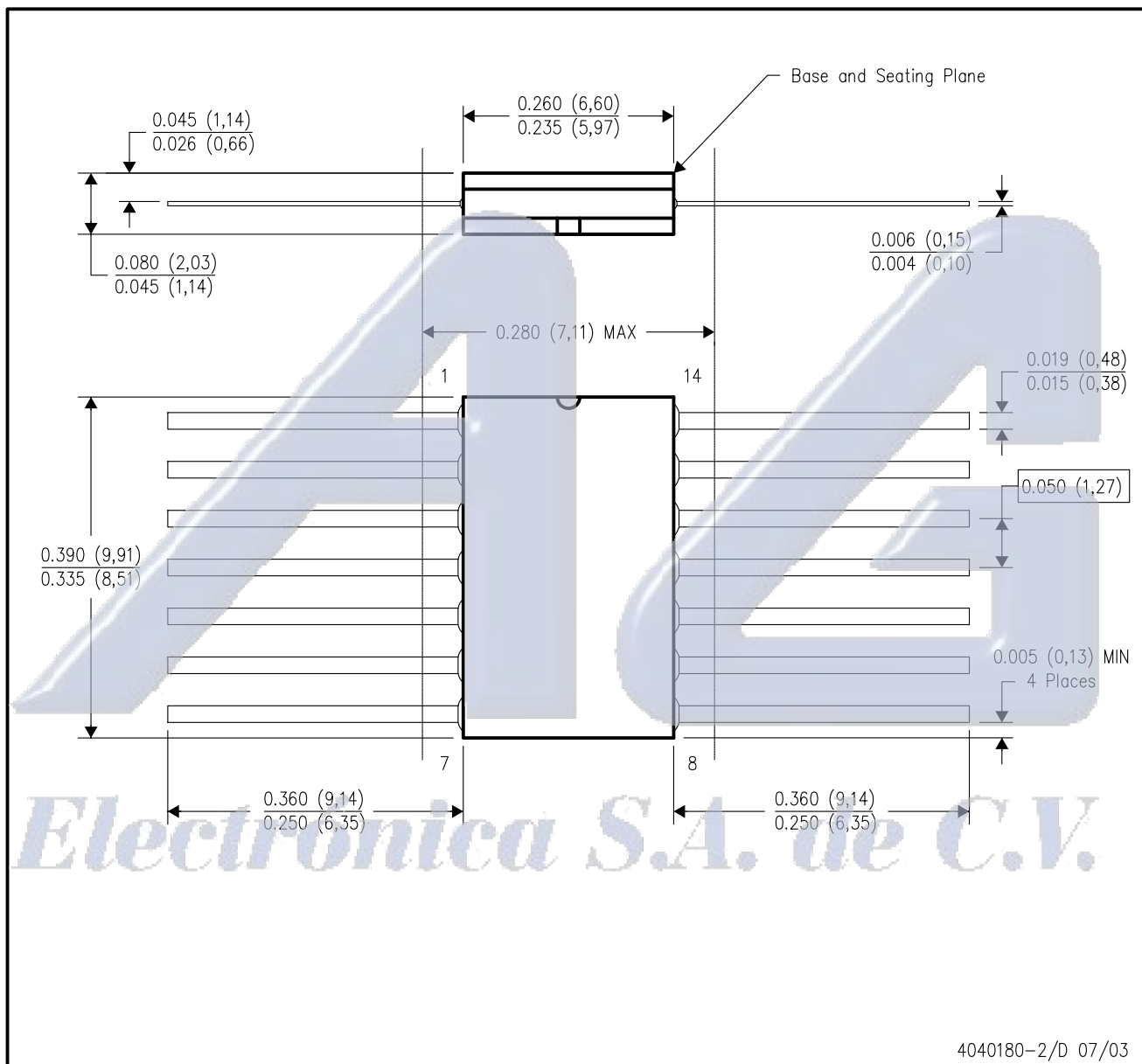


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



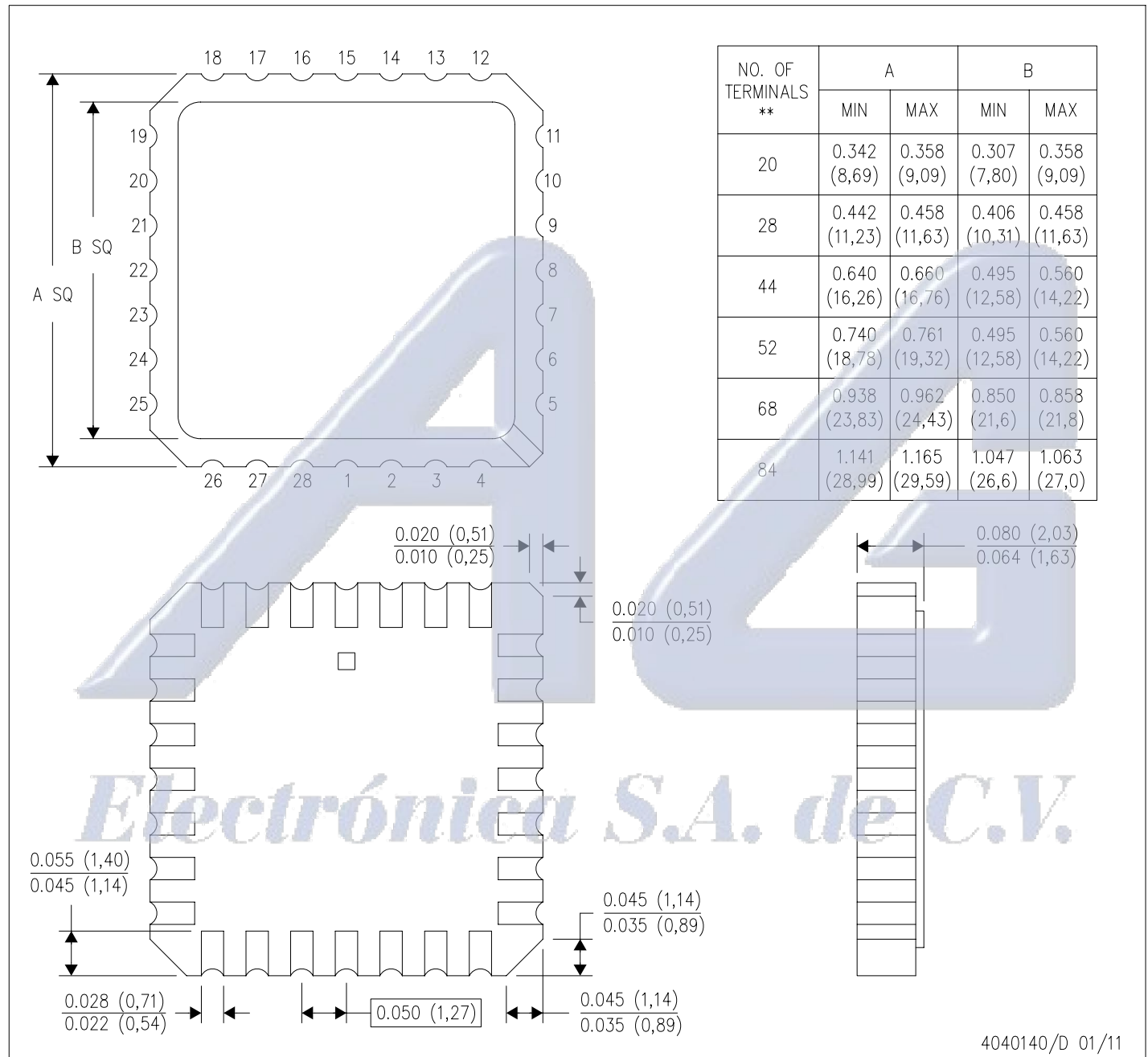
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. Falls within JEDEC MS-004

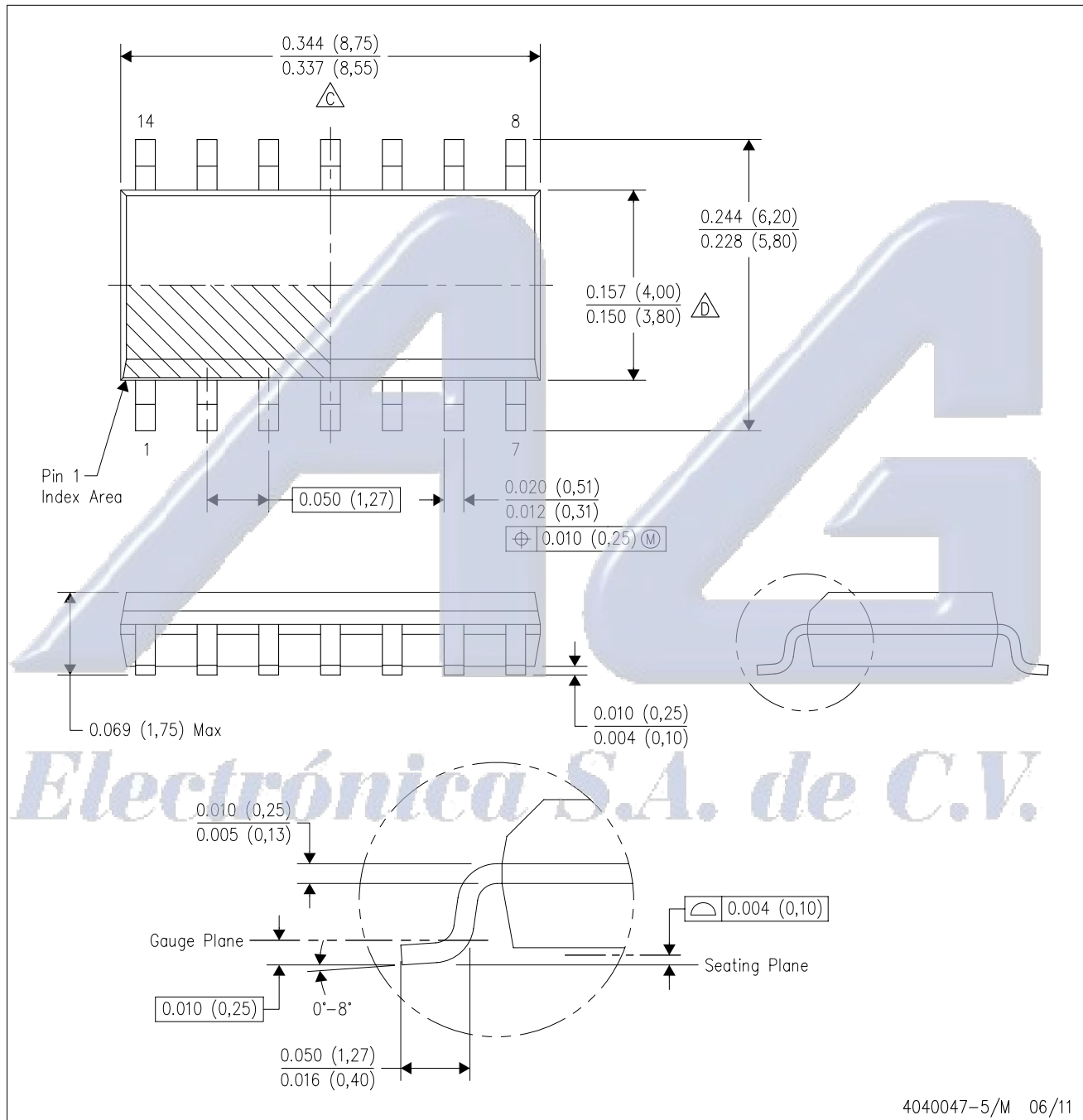




MECHANICAL DATA

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040047-5/M 06/11

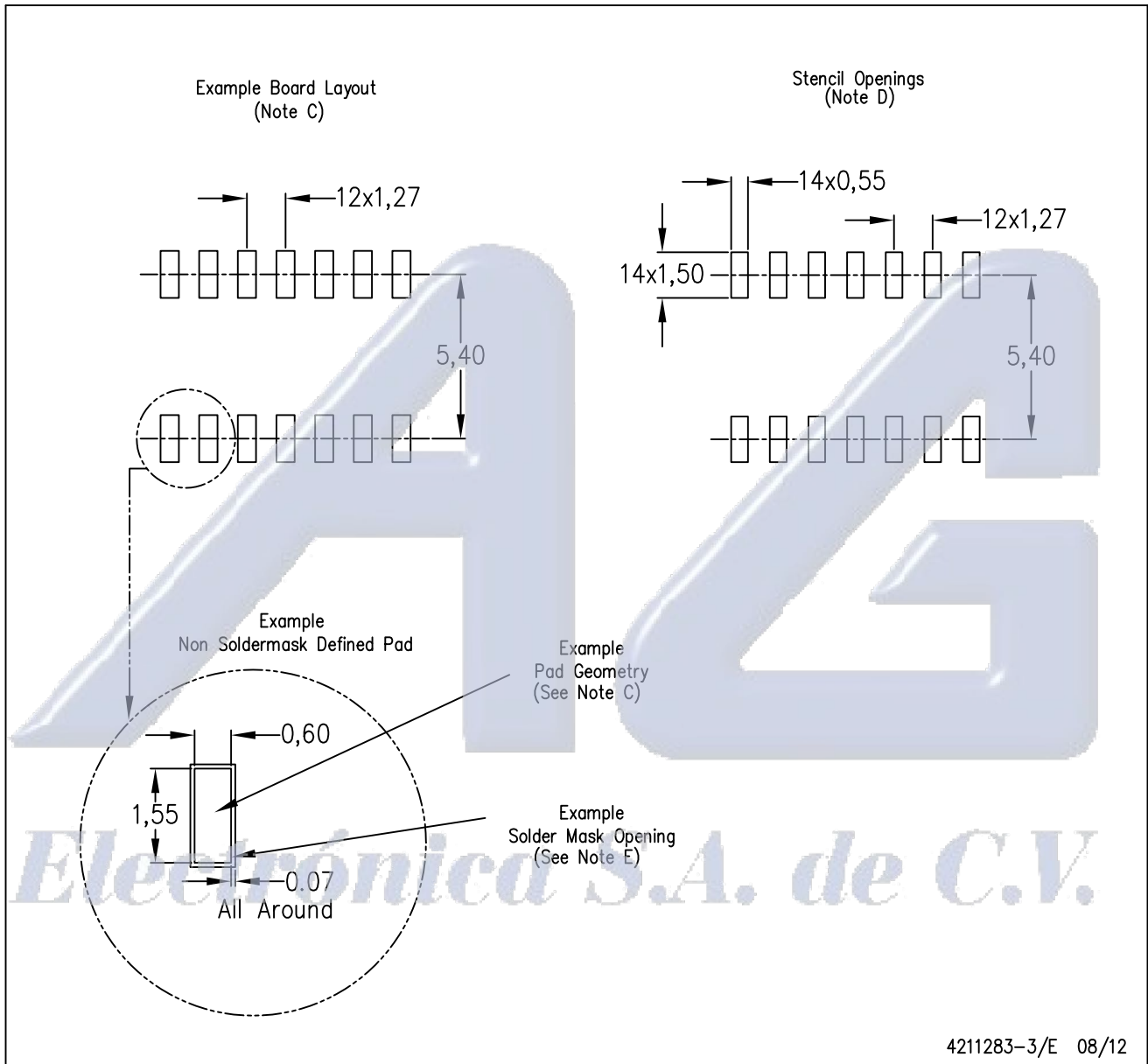
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.



LAND PATTERN DATA

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

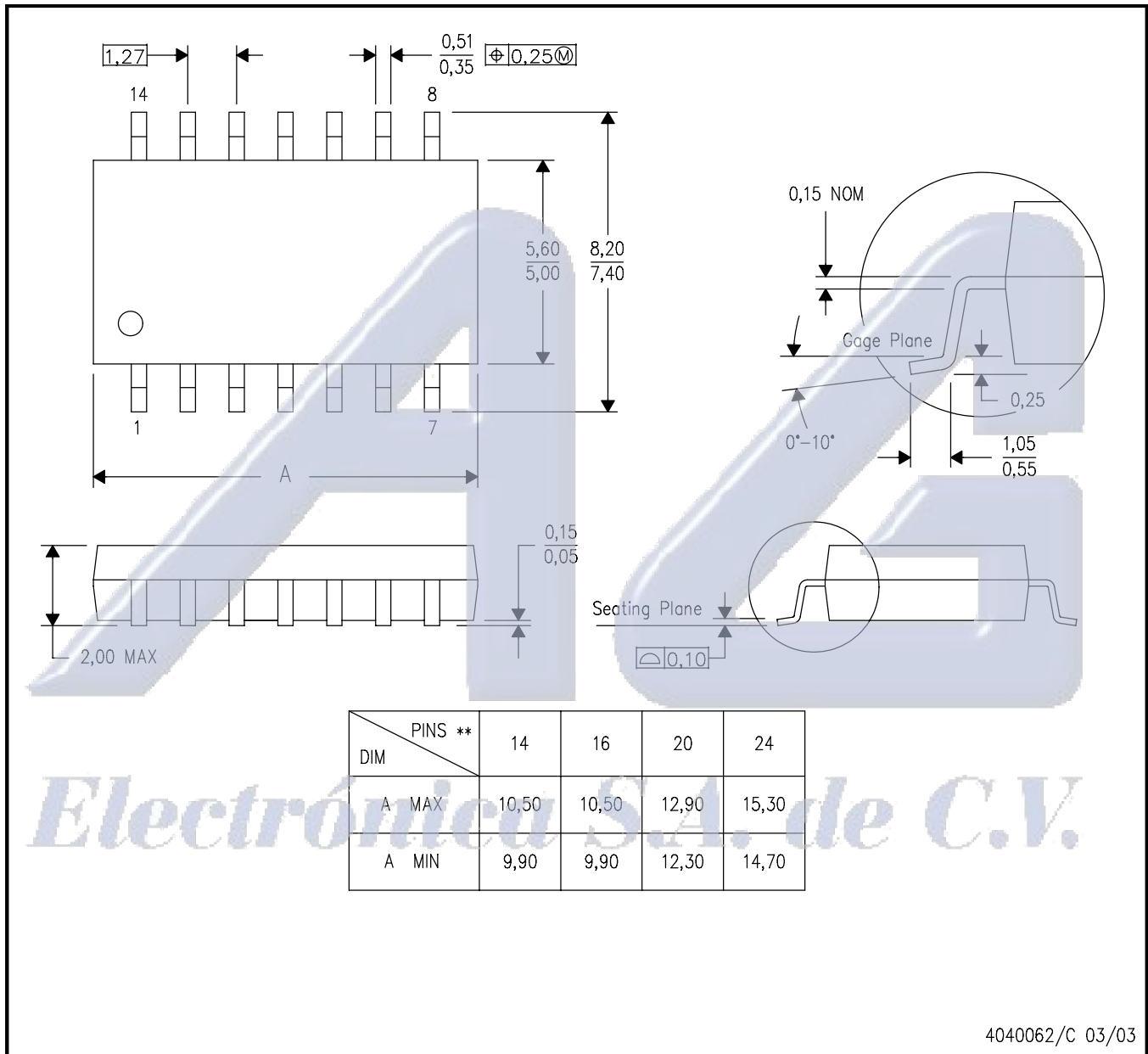
- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



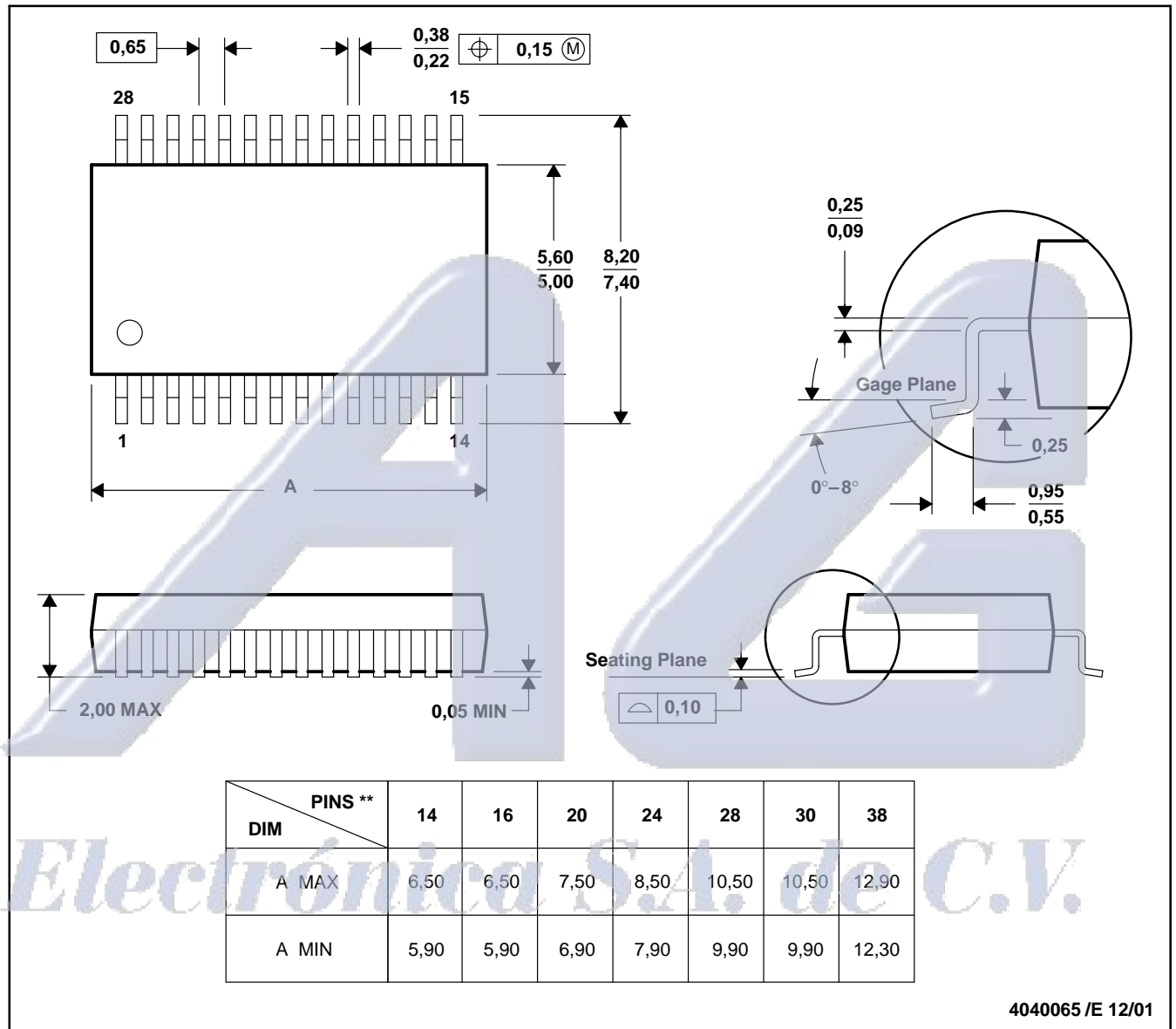
- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

4040065 / E 12/01